

May 2007

# 74ACTQ04 Quiet Series™ Hex Inverter

#### **Features**

- I<sub>CC</sub> reduced by 50%
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- Outputs source/sink 24mA
- Has TTL-compatible inputs

### **General Description**

The ACTQ04 contains six inverters and utilizes Fairchild Quiet Series™ technology to guarantee quiet output switching and improved dynamic threshold performance. FACT Quiet Series™ features GTO™ output control and undershoot corrector in addition to a split ground bus for superior ACMOS performance.

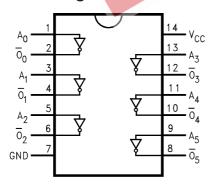
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# **Ordering Information**

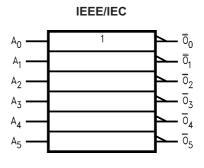
Order Number	Package Number	Package Description
74ACTQ04SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74ACTQ04SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACTQ04MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number. Pb-Free package per JEDEC J-STD-020B.

# **Connection Diagram**



## **Logic Symbol**



# **Pin Description**

Pin Names	Description
A <sub>n</sub>	Inputs
Ōn	Outputs

 $\mathsf{FACT}^{\intercal \mathsf{M}},\,\mathsf{FACT}\,\mathsf{Quiet}\,\mathsf{Series}^{\intercal \mathsf{M}},\,\mathsf{and}\,\,\mathsf{GTO}^{\intercal \mathsf{M}}\,\,\mathsf{are}\,\,\mathsf{trademarks}\,\,\mathsf{of}\,\,\mathsf{Fairchild}\,\,\mathsf{Semiconductor}\,\,\mathsf{Corporation}.$ 

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	-0.5V to +7.0V
I <sub>IK</sub>	DC Input Diode Current	
	$V_I = -0.5V$	–20mA
	$V_{I} = V_{CC} + 0.5V$	+20mA
VI	DC Input Voltage	–0.5V to V <sub>CC</sub> + 0.5V
I <sub>OK</sub>	DC Output Diode Current	
	$V_{O} = -0.5V$	–20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
Vo	DC Output Voltage	–0.5V to V <sub>CC</sub> + 0.5V
Io	DC Output Source or Sink Current	±50mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current per Output Pin	±50mA
T <sub>STG</sub>	Storage Temperature	–65°C to +150°C
	DC Latch-Up Source or Sink Current	±300mA
TJ	Junction Temperature	140°C

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V <sub>CC</sub>	Supply Voltage	4.5V to 5.5V
VI	Input Voltage	0V to V <sub>CC</sub>
Vo	Output Voltage	0V to V <sub>CC</sub>
T <sub>A</sub>	Operating Temperature	-40°C to +85°C
ΔV / Δt	Minimum Input Edge Rate:	125mV/ns
	V <sub>IN</sub> from 0.8V to 2.0V, V <sub>CC</sub> @ 4.5V, 5.5V	

## **DC Electrical Characteristics**

				$T_A = +$	-25°C	T <sub>A</sub> = -40°C to +85°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Тур.	G	uaranteed Limits	Units
V <sub>IH</sub>	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$	1.5	2.0	2.0	V
	Input Voltage	5.5	or V <sub>CC</sub> – 0.1V	1.5	2.0	2.0	
V <sub>IL</sub>	Maximum LOW Level	4.5	V <sub>OUT</sub> = 0.1V	1.5	0.8	0.8	V
	Input Voltage	5.5	or V <sub>CC</sub> – 0.1V	1.5	0.8	0.8	
V <sub>OH</sub>	Minimum HIGH Level	4.5	I <sub>OUT</sub> = -50μA	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	
			$V_{IN} = V_{IL}$ or $V_{IH}$ :				
		4.5	$I_{OH} = -24mA$		3.86	3.76	
		5.5	$I_{OH} = -24 \text{mA}^{(1)}$		4.86	4.76	
$V_{OL}$	Maximum LOW Level	4.5	$I_{OUT} = 50\mu A$	0.001	0.1	0.1	V
	Output Voltage	5.5		0.001	0.1	0.1	
			$V_{IN} = V_{IL} \text{ or } V_{IH}$ :		4	100	
		4.5	I <sub>OL</sub> = 24mA	4.	0.36	0.44	
		5.5	$I_{OL} = 24 \text{mA}^{(1)}$	花	0.36	0.44	
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$ , GND	OT	±0.1	±1.0	μA
I <sub>CCT</sub>	Maximum I <sub>CC</sub> /Input	5.5	$V_I = V_{CC} - 2.1V$	0.6		1.5	mA
I <sub>OLD</sub>	Minimum Dynamic	5.5	V <sub>OLD</sub> = 1.65V Max.			75	mA
$I_{OHD}$	Output Current <sup>(2)</sup>	5.5	$V_{OHD} = 3.85V$ Min.			<b>–</b> 75	mA
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		2.0	20.0	μA
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OL</sub>	5.0	Figures 1 & 2 <sup>(3)</sup>	1.1	1.5		V
V <sub>OLV</sub>	Quiet Output Minimum Dynamic V <sub>OL</sub>	5.0	Figures 1 & 2 <sup>(3)</sup>	-0.6	-1.2		V
V <sub>IHD</sub>	Minimum HIGH Level Dynamic Input Voltage	5.0	(4)	1.9	2.2		V
V <sub>ILD</sub>	Maximum LOW Level Dynamic Input Voltage	5.0	(4)	1.2	0.8		V

#### Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. Maximum test duration 2.0ms, one output loaded at a time.
- 3. Max number of outputs defined as (n). Data inputs are 0V to 3V. One output @ GND.
- 4. Max number of data inputs (n) switching. (n–1) inputs switching 0V to 3V. Input-under-test switching: 3V to threshold ( $V_{ILD}$ ), 0V to threshold ( $V_{IHD}$ ), f = 1MHz.

### **AC Electrical Characteristics**

			T <sub>A</sub> = +25°C, C <sub>L</sub> = 50pF		T <sub>A</sub> = -40°C C <sub>L</sub> =			
Symbol	Parameter	$V_{CC}(V)^{(5)}$	Min.	Тур.	Max.	Min.	Max.	Units
t <sub>PLH</sub>	Propagation Delay, Data to Output	5.0	2.0	6.5	7.5	2.0	8.0	ns
t <sub>PHL</sub>	Propagation Delay, Data to Output	5.0	2.0	6.5	7.5	2.0	8.0	ns
t <sub>OSHL</sub> , t <sub>OSLH</sub>	Output to Output Skew <sup>(6)</sup>	5.0		0.5	1.0		1.0	ns

#### Notes:

- 5. Voltage range 5.0 is  $5.0V \pm 0.5V$ .
- 6. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

# Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = OPEN	4.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance	$V_{CC} = 5.0V$	74	pF
		.60		

#### **FACT™** Noise Characteristics

The setup of a noise characteristics measurement is critical to the accuracy and repeatability of the tests. The following is a brief description of the setup used to measure the noise characteristics of FACT.

#### **Equipment:**

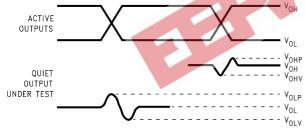
Hewlett Packard Model 8180A Word Generator

PC-163A Test Fixture

Tektronics Model 7854 Oscilloscope

#### Procedure:

- Verify Test Fixture Loading: Standard Load 50pF, 500Ω.
- Deskew the HFS generator so that no two channels have greater than 150ps skew between them. This requires that the oscilloscope be deskewed first. It is important to deskew the HFS generator channels before testing. This will ensure that the outputs switch simultaneously.
- 3. Terminate all inputs and outputs to ensure proper loading of the outputs and that the input levels are at the correct voltage.
- Set the HFS generator to toggle all but one output at a frequency of 1MHz. Greater frequencies will increase DUT heating and effect the results of the measurement.



#### Notes:

- V<sub>OHV</sub> and V<sub>OLP</sub> are measured with respect to ground reference.
- 8. Input pulses have the following characteristics: f = 1MHz,  $t_r = 3ns$ ,  $t_f = 3ns$ , skew < 150ps.

#### Figure 1. Quiet Output Noise Voltage Waveforms

5. Set the HFS generator input levels at 0V LOW and 3V HIGH for ACT devices and 0V LOW and 5V HIGH for AC devices. Verify levels with an oscilloscope.

### V<sub>OLP</sub>/V<sub>OLV</sub> and V<sub>OHP</sub>/V<sub>OHV</sub>:

- Determine the quiet output pin that demonstrates the greatest noise levels. The worst case pin will usually be the furthest from the ground pin. Monitor the output voltages using a  $50\Omega$  coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.
- Measure V<sub>OLP</sub> and V<sub>OLV</sub> on the quiet output during worst case transition for active and enable. Measure V<sub>OHP</sub> and V<sub>OHV</sub> on the quiet output during the worst case active and enable transition.
- Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

#### V<sub>ILD</sub> and V<sub>IHD</sub>:

- Monitor one of the switching outputs using a  $50\Omega$  coaxial cable plugged into a standard SMB type connector on the test fixture. Do not use an active FET probe.
- First increase the input LOW voltage level, V<sub>IL</sub>, until the output begins to oscillator steps out a min of 2ns. Oscillation is defined as noise on the output LOW level that exceeds V<sub>IL</sub> limits, or on output HIGH levels that exceed V<sub>IH</sub> limits. The input LOW voltage level at which oscillation occurs is defined as V<sub>ILD</sub>.
- Next decrease the input HIGH voltage level, V<sub>IH</sub>, until the output begins to oscillate or steps out a min of 2ns. Oscillation is defined as noise on the output LOW level that exceeds V<sub>IL</sub> limits, or on output HIGH levels that exceed V<sub>IH</sub> limits. The input HIGH voltage level at which oscillation occurs is defined as V<sub>IHD</sub>.
- Verify that the GND reference recorded on the oscilloscope has not drifted to ensure the accuracy and repeatability of the measurements.

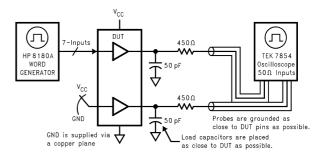
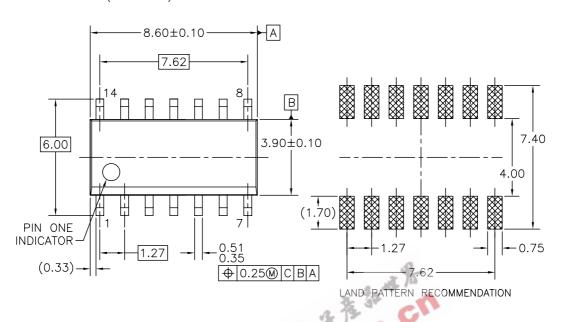


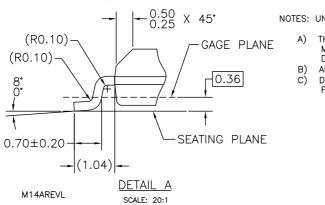
Figure 2. Simultaneous Switching Test Circuit

# **Physical Dimensions**

Dimensions are in inches (millimeters) unless otherwise noted.







NOTES: UNLESS OTHERWISE SPECIFIED

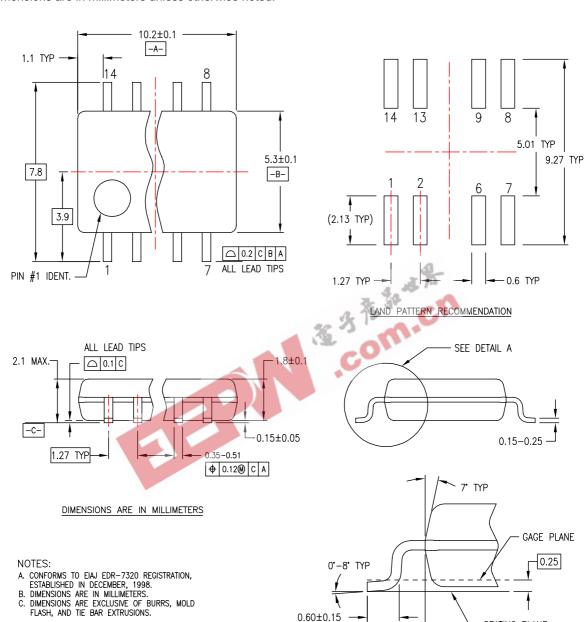
- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C, DATED MAY 1990.

  B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.

Figure 3. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A

# Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



M14DREVC

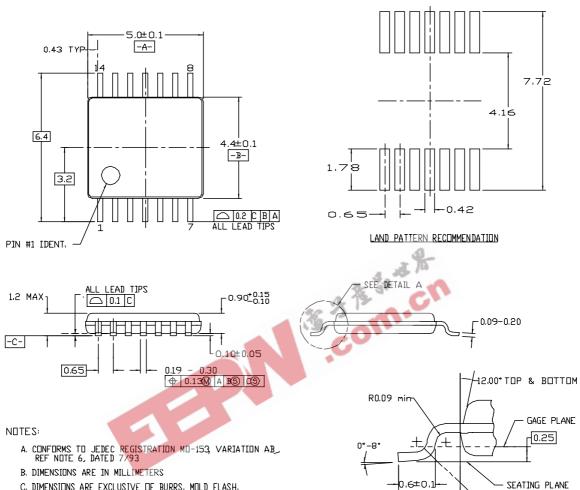
Figure 4. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M14D

SEATING PLANE

DETAIL A

# Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
  D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982

MTC14revD

Figure 5. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

R0,09min

1.00

DETAIL A





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